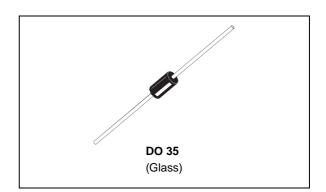


SMALL SIGNAL SCHOTTKY DIODE



DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching. Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic range.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive Peak Reverse Voltage	Repetitive Peak Reverse Voltage		
I _F	Forward Continuous Current*	15	mA	
I _{FSM}	Surge non Repetitive Forward Current*	50	mA	
T _{stg} T _j	Storage and Junction Temperature Range	- 65 to 200 - 65 to 200	°C	
TL	Maximum Lead Temperature for Soldering dur from Case	230	°C	

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
V_{BR}	T _{amb} = 25°C	$I_R = 10\mu A$		60			٧
V _F * *	T _{amb} = 25°C	I _F = 1mA				0.41	V
	T _{amb} = 25°C	$I_F = 15mA$				1	
I _R * *	T _{amb} = 25°C	$V_R = 50V$				0.2	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
О	$T_{amb} = 25^{\circ}C$	$V_R = 0V$	f = 1MHz			2.2	pF
τ	T _{amb} = 25°C	$I_F = 5mA$	Krakauer Method			100	ps

* On infinite heatsink with 4mm lead length
** Pulse test: $t_p \le 300 \mu s \delta < 2\%$.
Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

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Fig.1 : Forward current versus forward voltage (typical values).

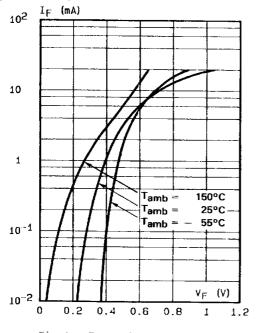


Fig.2 : Capacitance C versus reverse applied voltage V_R (typical values).

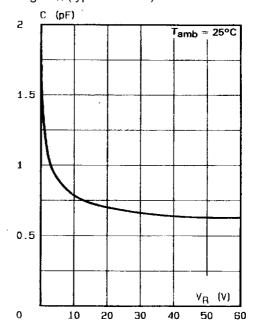


Fig.3: Reverse current versus ambient temperature.

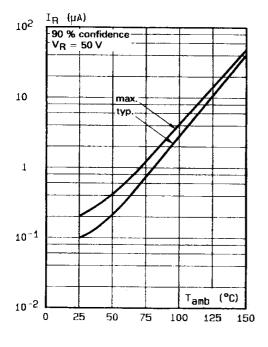
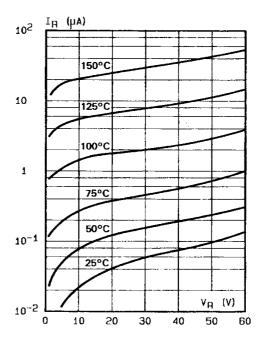


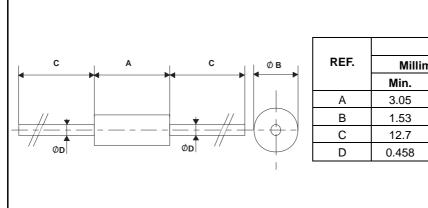
Fig.4: Reverse current versus continuous reverse voltage (typical values).



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PACKAGE MECHANICAL DATA

DO 35 Glass



	DIMENSIONS					
REF.	Millin	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	3.05	4.50	0.120	0.177		
В	1.53	2.00	0.060	0.079		
С	12.7		0.500			
D	0.458	0.558	0.018	0.022		

Cooling method : by convection and conduction Marking: clear, ring at cathode end. Weight: 0.15g

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